

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-119488

(43)Date of publication of application : 25.04.2000

(51)Int.Cl.

C08L 63/00
C08K 5/54

(21)Application number : 10-295008

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(22)Date of filing : 16.10.1998

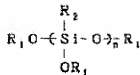
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(54) RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a resin composition for forming an excellent coating at a fast curing speed and with corrosion resistance, adherence, curability, solvent resistance and curing product properties by compounding an alkoxy silane compound and a modified epoxy resin added another alkoxy silane compound.

SOLUTION: A resin composition is obtained by compounding an alkoxy silane compound represented by the formula (wherein R₁ is 1-4C alkyl; R₂ is R₁O-, 1-8C alkyl and dryl; n is an integer of 1-10) into an epoxy compound having at least two epoxy groups, and a compound having at least one alkoxy silyl group and at least one epoxy group in a molecule and a modified epoxy resin (C) added a carboxylic acid according to demand. The epoxy compound is preferably aliphatic polyglycidyl ether particularly. The modified epoxy resin (C) is desirable to contain at least 10 mole% of a dicarboxylic acid on the basis of the whole carboxylic acid. A weight ratio of the modified epoxy resin/ the alkoxy silane compound is preferably 10/1-1/5.



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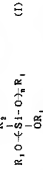
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2 *** shows the word which can not be translated.

3 In the drawings any words are not translated

CLAIMS

[Claim(a)]
[*]A resin composite which consists of a following (b) ingredient and a (*) ingredient.
[*]The modified epoxy resin (**) following produced by adding (c) carboxylic acid to an epoxy compound (**) which has two or more epoxy groups in the (a) molecule a compound which has a basis which can react to one or more alkoxy silyl groups and one or more epoxy groups in the (b) molecule, and if needed A removed expressed with several formula (f) of the zinc 1 [Chemical formula 1]



(5) 中、 R_1 は状態数 1~4 のアルキル基を表し、 R_2 は R_1 、 O 、炭素数 1~8 のアルキル基またはアリアル基を表し、 n は 1~10 を表す。）

[Claim 2](b). The resin composite according to claim 1 whose basis which can react to an epoxy group of an ingredient is an amino alkyl group.

[Claim 4] (4a) The resin composition according to any one of claims 1 to 3 which is an addition in which an ingredient added the (b) ingredient and the (c) ingredient to the (a) ingredient.

[Claim 5] (5a) The resin composition according to any one of claims 1 to 4 whose ingredient is the addition to which the (c) ingredient is added in the range of 0.1–0.9 Eq of carboxyl groups to 1 Eq of epoxy groups of the (a) ingredient.

[Claim 6] (6a) The resin composition according to any one of claims 1 to 5 whose epoxy compound of an ingredient is aliphatic oxazoline diisocyanate.

(claim 7)(c) an ingredient — a carboxylic acid — more than 10 mol % of all the carboxylic acid components — the resin composites according to any one of claims 1 to 6 which is what is included.

(claim 8)(b) The resin composite according to any one of claims 1 to 7 whose blending ratios of an emulsifier and a surfactant are $(h)/(g) \geq 0.1 - 1/5$ in a weight ratio.

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